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# **INDEX**

SESSION 2: Advanced Packaging I

Chair: G.S. Shen (Chipmos) C.E. Ho (YZU)

Time	Paper Code	Topic	Lead Author	Affiliation
15:00-15:15	TW025-2	Single Sided Heating Method for Chip- to-Wafer Bonding with Submicron Cu/In Interconnects	Ching-Yun Chang	National Chiao Tung University
15:15-15:30	TW040-1	Growth of Cu6Sn5 and Cu3Sn Intermetallic compounds on (111)-, (100)-, and randomly-oriented copper films	Yu-Jin Li	National Chiao Tung University
15:45-16:00	TW039-1	Grain growth of (111) Nanotwined Cu on (100)-oriented Cu films	Hsin-Yong Liu	National Chiao Tung University



SESSION 3: Electro Platinng Chair: Alex King (Taimide) Wei-Ping Dow (NCHU)

Time	Paper Code	Topic	Lead Author	Affiliation
14:30-14:45	TW028-1	Controlling the adhesion of electroless plating Ni-P film on silicon wafer by means of silane compound modification and rapid thermal annealing	Wei-Yan Wang	National Tsing Hua University
15:30-15:45	US002-1	Next Generation Electrolytic Copper Plating Process for HDI Applications	Nagarajan Jayaraju	Dow Electronic Materials
15:45-16:00	TW013-1	The new vertical continuous transport equipment, U-VCPS	JL. Huang	uyemura



SESSION 4: Emerging Tech / PCB

Chair: Eric Liao (TUC)

Chi-Shiung His (NUU)

Time	Paper Code	Topic	Lead Author	Affiliation
14:30-14:45	TW064-1	Integrated Humidity and Temperature Sensing Circuit Fabricated by Inkjet Printing Technology	Shih Chien Lin	National Taiwan University
14:45-15:00	AS024-1	Laser Dicing for Higher Chip Productivity	Natsuki Suzuki	Hamamatsu Photonics K.K.
15:00-15:15	TW050-1	Design of Printed Circuit Board with Separate Heat Metal Block for High-Speed Optical Transceiver Module	Chiu Chun-Lin	National Kaohsiung University of Applied Sciences
15:30-15:45	AS005-1	Novel Approach for Search Engine and Data Compression Transceiver	Kanji Otsuka	Meisei University
15:45-16:00	TW075-1	Wearable Multi-lead ECG Recorder with Dry Metal Electrodes	Terng-Ren Hsu	Chung Hua University



#### SESSION 6: Interconnection

Chair: Max Lu (SPIL)

Andreas Ostmann (Fraunhofer IZM)

Time	Paper Code	Topic	Lead Author	Affiliation
17:15-17:30	AS009-1	A Potential Silver Catalyst System for New Generation of Electroless Cu Process as a Palladium Substitution	Lok Lok Liu	Dow Electronic Materials
17:45-18:00	EU005-1	Laser structured PDMS gasket as void-free underfill material for implantable biomedical microsystems	sharif khan	IMTEK, University of freiburg
18:00-18:15	TW055-1	Effect of Sn Grain Orientation on the Formation of Cu6Sn5 Intermetallic Compounds during Electromigration	Yu-An Shen	National Chiao Tung University



SESSION 7: Modeling & Design I Chair: Jack Chang Chien (PTI) Hsien-Chie Cheng (FCU)

Time	Paper Code	Topic	Lead Author	Affiliation
16:45-17:00	TW112-1	Characterization of Through Glass Via (TGV) RF Inductors	Yu-Chang Hsieh	Advanced Semiconductor Engineering, Inc.
17:00-17:15	TW081-1	Lidded FCCSP Warpage Evaluation: Process Modeling and Characterization of the Effect of Viscoelasticity and Cured Shrinkage for Molded Underfill	Shu-Shen Yeh	TSMC
17:30-17:45	TW057-1	Electrical Characterization for Performance- driven Printed Circuit Board	hellen lo	НРЕ
17:45-18:00	TW084-1	Characteristic Study of Anand and Modified Anand Creep Models for Area Array type WLCSP	Velsankar Ramachandran	National Tsing Hua University
18:00-18:15	AS023-1	Hybrid-Cascaded Modeling Strategy for 28Gbps High-Speed Transceivers in High- Density FPGA Packages	Chit Zhung Tan	Intel



#### SESSION 8: Emerging Tech / Substrate

Chair: Algo Lin (Taiflex)
Gallen Wu (UL)

Time	Paper Code	Topic	Lead Author	Affiliation
16:45-17:00	TW047-1	Flex Circuit Depaneling in Thin Film Polymer Using Dry Etching Technology	Jim-Wein Lin	Unimicron
17:00-17:15	TW051-2	Low Temperature and Pressureless Cu-to-Cu Bonding By Electroless Nickel Plating	Sean Yang	National Taiwan University
17:30-17:45	TW026-1	Inkjet Printing of Nano-Silver Conductive Lines on Polyimide Substrates	ChiaYen Chan	ITRC, NARL
18:00-18:15	AS026-1	Drilling characteristics of entry board and the influence on PCB micro drilling process	Xin Huang	Guangdong University of Technology



SESSION 12: Emerging Systems / Packaging

Chair: Wendy Chen (KYEC) Walter Jau (ASE)

Time	Paper Code	Topic	Lead Author	Affiliation
11:30-11:45	EU002-1	One-Time Deformable Thermoplastic Devices Based on Flexible Circuit Board Technology	Bart Plovie	Cmst (imec - UGent)
11:45-12:00	TW014-2	The Reaction Mechanism of Cupric Oxide Reduction under Hydrogen Plasma Treatment for Epoxy Molding Compound / Lead-Frames Adhesion Improve	Min-Fong Shu	Advanced Semiconductor Engineering, Inc.
12:00-12:15	TW029-1	A Silicon-based Dual-LED Packaging Module with a Three-dimension Freeform Lens for Square Illumination	Liou Cheng-shiun	Feng Chia University
12:15-12:30	TW044-1	Study of Nano-twinned Cu Prepared by Low- temperature Electrodeposition and Its Thermal Stability	Yen-Chieh Chen	National Chiao Tung University



#### SESSION 15: Advanced Packaging Chair: Li-Cheng Shen (WNC)

Chang-Chun Lee (NCHU)

Time	Paper Code	Торіс	Lead Author	Affiliation
14:15-14:30	AS007-1	Board Level Reliability Improvement in eWLB (Embedded Wafer Level BGA) Packages	Seung Wook Yoon	Statschippac Pte LTD
14:30-14:45	AS010-1	Thin Profile Flip Chip Package-on-Package Development	Ming-Che Hsieh	STATS ChipPAC Pte. Ltd.
14:45-15:00	AS022-1	Observation and Analysis of Metal Oxide Reduction by Formic Acid for Soldering	Naoto Ozawa	Origin Electric Co., Ltd.
15:00-15:15	TW107-1	Lowering Coupling Noise between Chips in System-in-Package (SiP) Module Using Compartment Shielding	Fu-Chen Chu	Advanced Semiconductor Engineering, Inc.



#### SESSION 16: PCB Reliability

Chair: Jeffrey Lee (IST) Chih Chen (NCTU)

Time	Paper Code	Topic	Lead Author	Affiliation
14:00-14:15	TW034-1	Creep Corrosion on High Reliability Printed Circuit Boards.	Tsan-Hsien Tseng	National Central University
14:15-14:30	TW102-1	Evaluation of the Anti-Corrosion Capacity for Various Electronics by Way of Accelerated Corrosion Testing Platform	Dem Lee	Integrated Service Technology Inc.
14:30-14:45	AS021-1	Evaluation of Bonding Strength of Thin Copper Wire and Lead-Free Solder by Pullout Tests	Naoya Tada	Okayama University
14:45-15:00	TW080-1	Non-uniformity Evaluation of Flat Panel Display by Automatic Optical Detection	Fu Ming Tzu	National Kaohsiung Marine University
15:00-15:15	TW043-1	Experimental Design and Evaluation of Dielectric Profile of Printed Circuit Boards	Kuen-Fwu Fuh	National United University



#### SESSION 19: Modeling & Design II Chair: William Chao (CISCO) Kuo-Ming Chen (UMC)

Time	Paper Code	Topic	Lead Author	Affiliation
16:20-16:35	TW045-1	Analysis and Design of Connection between Flexible PCB and Hard PCB for 25 Gb/s Optical Subassembly Module	Su Zhe-Xian	National Kaohsiung University of Applied Sciences
16:35-16:50	TW083-1	Finite Element Mesh Size Effect for Reliability Assessment of WLCSP using Different Creep Theories	Pei-Lun Wu	National Tsing Hua University
16:50-17:05	TW076-1	Design optimization for wafer level package by using sequential optimization and reliability assessment method	Tz-Cheng Chiu	National Cheng Kung University
17:05-17:20	AS008-1	Crosstalk and SSO noise minimize optimization of high speed and high-pin-count 3D PKG-VERTICAL CONNECTION UNIT	Steven Ma	SanDisk



#### SESSION 20: Electro Platinng / Chemicals

Chair: Irving Lee (UL) Crystal Lin (NPC)

Time	Paper Code	Topic	Lead Author	Affiliation
16:05-16:20	AS015-2	New Immersion Gold Technology for Uniform Au Thickness Distribution	Jian Zhang	Dow Electronic Materials
16:50-17:05	TW077-2	The Study of Warpage of a Flip Chip Embedded Trace Substrate	Ming Chang Shih	National Kaohsung University
17:20-17:35	TW053-1	Fabrication and characterization of electroplated nanotwinned-copper films on polymer substrates	Liang-Hsien Chang	National Chiao Tung University



#### SESSION 22: Advanced Materials / Packaging

Chair: Vincent Wei (THEIL) Ben-Je Lwo (NDU)

Time	Paper Code	Topic	Lead Author	Affiliation
11:00-11:15	AS001-1	Phase Equilibria of the Sn-Ni-W Ternary System at 750 °C	Gita Novian Hermana	National Taiwan University of Science and Technoloy
12:00-12:15	US003-1	The Effect of Reworkable Edgebond Adhesives on the Board Level Reliability of Larger WLCSP's	Simon Chang	Zymet Incorp.
12:15-12:30	TW035-1	The Development of IC Packaging under the Internet of Things Standards	Alice Lin	Integrated Service Technology Inc.



### SESSION 23: Thermal / Packaging

Chair: Chien-Yuh Yang (NCU) Allen Liu (ITRI)

Time	Paper Code	Topic	Lead Author	Affiliation
11:00-11:15	AS025-1	CFD Analysis about Surface Roughness Dependence of Thermal Contact Resistance	Tomoyuki Hatakeyama	Toyama Prefectural University
11:30-11:45	AS016-1	Transient Electro-Thermal Simulation of Multi- Channel Power Switch Device in Enhanced SOIC Package	Cheong Chiang Ng	NXP Semiconductors
11:45-12:00	TW038-1	Mechanical properties of highly (111)-oriented nanotwinned Cu lines	Wei-Ling Lai	National Chiao Tung University
12:00-12:15	TW126-1	Using Silicone as Protective Layer Stacked under BGA for Lowering Temperature in PVD Process	Shih-Chun Chen	PTI
	TW146-1	Thermal-sprayed nanostructured silver particles for interconnect applications	Rong-Ting Liou	National Chung Hsing University



#### SESSION 24: Advanced Materials / PCB

Chair: Wood Chuang (Inventec) Shih-Kang Lin (NCKU)

Time	Paper Code	Торіс	Lead Author	Affiliation
11:00-11:15	AS019-1	High Performance Cyanide-free Immersion Gold	Willetta Lai	Dow Electronic Materials
11:15-11:30	EU001-1	CupraEtch™ FH: New, advanced, low- etch depth soldermask and photoresist pretreatment	Wonjin Cho	Atotech Deutschland GmbH
11:30-11:45	AS018-1	Study of LiTaO <sub>3</sub> /ST-quartz Bonding with Amorphous Interlayer Assisted by VUV/O <sub>3</sub> Treatment for SAW Device	Haruka Suzaki	Waseda University
12:00-12:15	TW086-1	Study on A Formulated No Clean Flux For Fine-Pitch Flip Chip Package of Copper Pillar/ Microbump Interconnect	Ya-Ching Chuang	Shenmao Technology Inc.



#### SESSION 25: Wearable Chair: Lewis Huang (Senju)

Time	Paper Code	Topic	Lead Author	Affiliation
13:45-14:00	EU003-1	Investigations in Selective Laser Melting as Manufacturing Technology for theProduction of High-temperature Mechatronic Integrated Devices	Aarief Syed Khaja	Friedrich-Alexander- University Erlangen- Nuremberg
14:15-14:30	TW008-1	A Gray Prediction GM(1,1) Fall Detection Signal Analysis and Implement in Wearable Device	Chao-Ting Chu	Chunghwa Telecom Co. Ltd.
14:45-15:00	TW094-1	Novel Wearable Device for Blood Leakage Detection during Hemodialysis Using an Array Sensing Patch	CIOU Wei-Siang	Southern Taiwan University of Science and Technoloy
15:00-15:15	TW022-1	A Dual Band Divide by Four Frequency Divider for Biomedical Sensor and Wearable Applications	Wen-Cheng Lai	National Taiwan University of Science and Technoloy
15:15-15:30	TW065-1	High Current Sustainable Circuits Prepared by Spray Pyrolyzed Silver Particles	Chi-Nan Cheng	National Chung Hsing University
15:30-15:45	TW022-2	A 4.9GHz Low Power QVCO Using Injection Locked Techniques for Wireless Wearable Applications	Wen-Cheng Lai	National Taiwan University of Science and Technoloy



### SESSION 26: SIP- System in Package

Chair: Jeffrey Chiou (ITRI)

Time	Paper Code	Торіс	Lead Author	Affiliation
13:45-14:00	AS020-1	Simultaneous Fabrication of a Through-Glass Interconnect Via and Bumps Using Dry Filling Process of Submicron Gold Particles	Kazuya Nomura	Waseda University
14:15-14:30	TW056-1	Backside-TSV process development and integration for 2~3um small size TSV	Chang Po Chih	Industrial Technology Research Institute (ITRI)
14:30-14:45	TW104-1	Determination of Strength of Si Interposers Using PoEF Test Associated with Acoustic Emission Method	Ming-Yi Tsai	Chang Gung University
14:45-15:00	TW009-1	SiP Assembly and Application using Glass Substrate with Through Vias	Ra-Min Tain	Unimicron
15:00-15:15	TW101-1	3D Architecture Exploration on Thermal Effect of DRAM Refresh	Wei-Kai Cheng	Chung Yuan Christian University
15:15-15:30	TW079-1	Applications of Film over Wire and Die Attach Film in Stacked Chip Scale Package	Liang Jui-Wen	I-Shou University



SESSION 27: Modeling & Design III

Chair: Jimmy Hsu (Intel) Yeong-Shu Chen (YZU)

Time	Paper Code	Topic	Lead Author	Affiliation
13:45-14:00	TW110-1	Practical Aspects for 3D Simulation of Underfill Encapsulation	Chia-Peng Sun	Moldex3D (CoreTech System Co., Ltd.)
14:30-14:45	TW119-1	Piezoelectric Effect on Transition Behavior in Large Deflection of Layered-bossed Plate under Pretension	Chun-Fu Chen	Chung Hua University
14:45-15:00	TW015-2	Deformation Prediction of 2.5D IC Package	Ming-Han Wang	Advanced Semiconductor Engineering, Inc.



SESSION 28: Advanced Packaging II

Chair: Hung-Yin Tsai (NTHU) Ho-Chiao Chuang (NTUT)

Time	Paper Code	Торіс	Lead Author	Affiliation
13:15-13:45	INVITED EU004-1	MultiPlate™ - From Wafer to Panel- New Solutions for Electrolytic Cu Deposition in Advanced Packaging	Bernd Roelfs	Atotech Deutschland GmbH
14:15-14:30	AS014-1	Development of liquid, granule, and sheet Type Epoxy Molding Compounds for Fan out Wafer/Panel level package.	Kenichi UENO	Sanyu-rec co, ltd.
14:45-15:00	TW042-1	Effect of additives on the microstructures of highly-oriented (111) nanotwinned Cu	Chen Kuan Ju	National Chiao Tung University
15:15-15:30	TW015-1	Novel Design for High Thermal Performance and SMT Process Yield QFP	Ming-Han Wang	Advanced Semiconductor Engineering, Inc.



### Poster Session\_Packaging

Venue: 5F, Taipei Nangang Exhibition Center

Paper Code	Topic	Lead Author	Affiliation
AS011-1	Effect of Electroless Ni-P thickness on EFTECH-64 and C194 Cu alloy.	Cheng Guan Ong	Infineon Technology (M) Sdn Bhd
TW005-1	Enhancement for gene transfection of bacteria in chip using magnetic attraction	Yung-Chiang Chung	Ming Chi University of Technology
TW007-1	Wireless Cloud Interaction System Implement Motor Control	Yung-Sheng Chang	National Yunlin University of Science and Technolo
TW007-2	Intelligent Integrate System Control for Smart Home	Yung-Sheng Chang	National Yunlin University of Science and Technolo
TW016-9	Performance Analyses on an Advanced High-power Diode Packaging Structures	Yong-Cheng Lu	National Defense University
TW018-1	Reliability Evaluation of Glass Interposer Module	Ching Kuan Lee	Industrial Technology Research Institute (ITRI)
TW021-1	Evaluation the reliability performance of new developed UP reflector in mid/high power SMD LED applications	Chih-Hao Lin	Industrial Technology Research Institute (ITRI)
TW024-1	Large Size WLCSP Analysis on Temperature Cycling Reliability Test	Sean Shih	Advanced Semiconductor Engineering, Inc.
TW030-1	Nanomechanical properties and fracture behaviors of GaN and Al0.08Ga0.92N thin films deposited on c-plane sapphire by MOCVD	Chia-Cheng Huang	Advanced Semiconductor Engineering, Inc.
TW046-8	Layer Assignment for Maximizing The Reliability of 3D ICs	Shih-Hsu Huang	Chung Yuan Christian University
TW059-1	Design and Experimental Analysis for Innovative Wide Bandwidth Vibration Sensor	Chih-Che Lin	Industrial Technology Research Institute (ITRI)
TW082-1	Silicon-carbide coating as mechanical enhancement for solar module assembly	HsinHsin Hsieh	Industrial Technology Research Institute (ITRI)
TW092-2	Advanced Nano-Ag Thermal Interface Material for High Thermal Flip Chip BGA	ChiTung Yeh	Siliconware Precision Industries Co., Ltd.
TW096-1	Shielding Effectiveness Modeling and Measurement of Multiple Layers Conformal Shielding on System-in-Package (SiP) Module	Hung Chun Kuo	National Sun Yat-sen University
TW122-2	Chip Package Interaction Development of Flip Chip CSP Package with Cu Pillar Bump on Lead for Advanced Node Chip	Chung Yen Wu	UMC
TW125-1	The surface modification of substrate for roughness improvement	Huei Nuan Huang	Siliconware Precision Industries Co., Ltd.



# Poster Session\_PCB

#### Venue: 5F, Taipei Nangang Exhibition Center

Paper Code	Торіс	Lead Author	Affiliation
TW012-1	Taguchi DoE for Ceramic Substrate SMT Defect Improvement	Ching Shan Chien	USI
TW019-1	The Component Drop-off Caused by Gold Embrittlement	Chun Chi Chiu	USI
TW027-1	A Composite Structure of High Frequency Low Dielectric Film and the Application in Flexible Printed Circuit (FPC)	Wei-Chih Lee	Asia Electronic Material Co., Ltd
TW032-1	Effect of Sulfonic Dopant Concentration on the Polymerization Degree of Poly(3,4-ethylenedioxythiophene) Synthesized by Oxidative Chemical Polymerization	Shih-Yun Huang	National Tsing Hua University
TW046-9	Reliability-Driven High-Level Synthesis with Clock Frequency Considered	Shih-Hsu Huang	Chung Yuan Christian University
TW049-1	Optimized Design of Through-Hole Via in High-Speed Printed Circuit Board	Sie Kun-Lin	National Kaohsiung University of Applied Sciences
TW063-1	Synthesis and Characterization of Polymerized 3-Aminophenyl Phosphonic Acid Prepared in the Presence of p-Phenylenediamine	Wei Ling Hsu	National Tsing Hua University
TW070-1	Identification of Flight Safety Zones for Unmanned Aerial Systems Using Geo-Fencing Data Provided by Prebuilt Maps	Eric Wang	International Bilingual School at Hsinchu Science
TW077-1	The Characterization of Solder Ball Strength Fatigue in Thermal Cycling Test	Ming Chang Shih	National Kaohsung University
TW080-2	Protrusive Detection for Thin Film Transistor-Liquid Crystal Display Using Side-view Illumination	Fu Ming Tzu	National Kaohsiung Marine University
TW095-1	Development of an Integrated System of 3D Printer and Laser Carving	Cheng-Tiao Hsieh Hsieh	Ming Chi University of Technology
TW099-1	The Failure Mode Study of the Polymer Ball Interconnected IC Package under Board Level Thermal Mechanical Stress	Cheng Chih Chen	Integrated Service Technology Inc.
TW108-1	Printing Functional Substrate for Flexible Electronics	WeiHan Hsiao	Industrial Technology Research Institute (ITRI)
TW113-1	Advanced Materials with Low Dielectric Properties and Highly Thermal Conductivity	Feng-Po Tseng	Industrial Technology Research Institute (ITRI)